

## Complementary Trench MOSFET

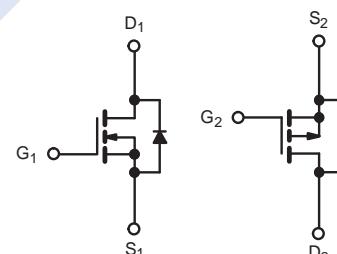
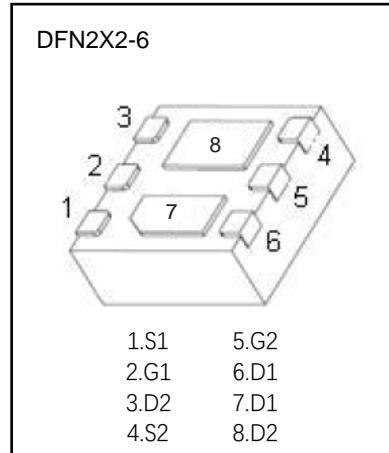
### 2NP03

#### ■ Features

- N-Channel
  - $V_{DS} (V) = 12V$
  - $I_D = 4.5 A (V_{GS} = 4.5V)$
  - $R_{DS(ON)} < 29m\Omega (V_{GS} = 4.5V)$
  - $R_{DS(ON)} < 34m\Omega (V_{GS} = 2.5V)$
  - $R_{DS(ON)} < 44m\Omega (V_{GS} = 1.8V)$
  - $R_{DS(ON)} < 65m\Omega (V_{GS} = 1.5V)$

#### P-Channel

- $V_{DS} (V) = -12V$
  - $I_D = -4.5 A (V_{GS} = -4.5V)$
  - $R_{DS(ON)} < 61m\Omega (V_{GS} = -4.5V)$
  - $R_{DS(ON)} < 81m\Omega (V_{GS} = -2.5V)$
  - $R_{DS(ON)} < 115m\Omega (V_{GS} = -1.8V)$
  - $R_{DS(ON)} < 170m\Omega (V_{GS} = -1.5V)$



N-Channel MOSFET    P-Channel MOSFET

#### ■ Absolute Maximum Ratings $T_a = 25^\circ C$

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	$V_{DS}$	12	-12	V
Gate-Source Voltage	$V_{GS}$	$\pm 8$		A
Continuous Drain Current	$I_D$	4.5	-4.5	
		4.5	-4.5	
		4.5	-4.3	
		4.5	-3.8	
Pulsed Drain Current	$I_{DM}$	20	-15	W
Power Dissipation	$P_D$	6.5		
		5		
		1.9		
		1.2		
Thermal Resistance.Junction- to-Ambient	$t \leqslant 5s$	$R_{thJA}$	65	°C/W
Thermal Resistance.Junction- to-Case	$R_{thJC}$		16	
Junction Temperature	$T_J$		150	
Storage Temperature Range	$T_{stg}$	-55 to 150		°C

## Complementary Trench MOSFET

### 2NP03

■ Electrical Characteristics Ta = 25°C

Parameter	Symbol	Test Conditions	Type	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V <sub>DSS</sub>	I <sub>D</sub> =250 uA, V <sub>GS</sub> =0V	N-CH	12			V
		I <sub>D</sub> =-250 uA, V <sub>GS</sub> =0V	P-CH	-12			
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =12V, V <sub>GS</sub> =0V	N-CH		1		uA
		V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V	P-CH		-1		
		V <sub>DS</sub> =12V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	N-CH		10		
		V <sub>DS</sub> =-12V, V <sub>GS</sub> =0V, T <sub>J</sub> =55°C	P-CH		-10		
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V	N-CH		±100		nA
		V <sub>DS</sub> =0V, V <sub>GS</sub> =±8V	P-CH		±100		
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 uA	N-CH	0.4	1		V
		V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =-250 uA	P-CH	-0.4	-1		
Static Drain-Source On-Resistance	R <sub>D(on)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5A	N-CH		29		mΩ
		V <sub>GS</sub> =2.5V, I <sub>D</sub> =4.6A			34		
		V <sub>GS</sub> =1.8V, I <sub>D</sub> =4.1A			44		
		V <sub>GS</sub> =1.5V, I <sub>D</sub> =2A			65		
		V <sub>GS</sub> =-4.5V, I <sub>D</sub> =-3.6A	P-CH		61		
		V <sub>GS</sub> =-2.5V, I <sub>D</sub> =-3.2A			81		
		V <sub>GS</sub> =-1.8V, I <sub>D</sub> =-1A			115		
		V <sub>GS</sub> =-1.5V, I <sub>D</sub> =-1A			170		
On-State Drain Current	I <sub>D(on)</sub>	V <sub>DS</sub> ≥5 V, V <sub>GS</sub> = 4.5 V	N-CH	15			A
		V <sub>DS</sub> ≥-5 V, V <sub>GS</sub> = -4.5 V	P-CH	-10			
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> =10V, I <sub>D</sub> =5A	N-CH		21		S
		V <sub>DS</sub> =-10V, I <sub>D</sub> =-3.6A	P-CH		11		
Input Capacitance	C <sub>iss</sub>	N-Channel: V <sub>GS</sub> =0V, V <sub>DS</sub> =6V, f=1MHz P-Channel: V <sub>GS</sub> =0V, V <sub>DS</sub> =-6V, f=1MHz	N-CH		500		pF
Output Capacitance	C <sub>oss</sub>		P-CH		590		
Reverse Transfer Capacitance	C <sub>rss</sub>		N-CH		160		
Gate Resistance	R <sub>g</sub>		P-CH		280		
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> =0V, f=1MHz	N-CH	0.7		7	nC
		V <sub>GS</sub> =8V, V <sub>DS</sub> =6V, I <sub>D</sub> =6.5A	N-CH		9.7	15	
		V <sub>GS</sub> =-8V, V <sub>DS</sub> =-6V, I <sub>D</sub> =-4.5A	P-CH		13.1	20	
		N-Channel: V <sub>GS</sub> =4.5V, V <sub>DS</sub> =6V, I <sub>D</sub> =6.5A P-Channel: V <sub>GS</sub> =-4.5V, V <sub>DS</sub> =-6V, I <sub>D</sub> =-4.3A	N-CH		5.6	8.5	
Gate Source Charge	Q <sub>gs</sub>		P-CH		8.2	12.5	
Gate Drain Charge	Q <sub>gd</sub>		N-CH		0.72		
			P-CH		1.2		
			N-CH		0.74		
			P-CH		2.8		

## Complementary Trench MOSFET

### 2NP03

■ Electrical Characteristics  $T_a = 25^\circ C$

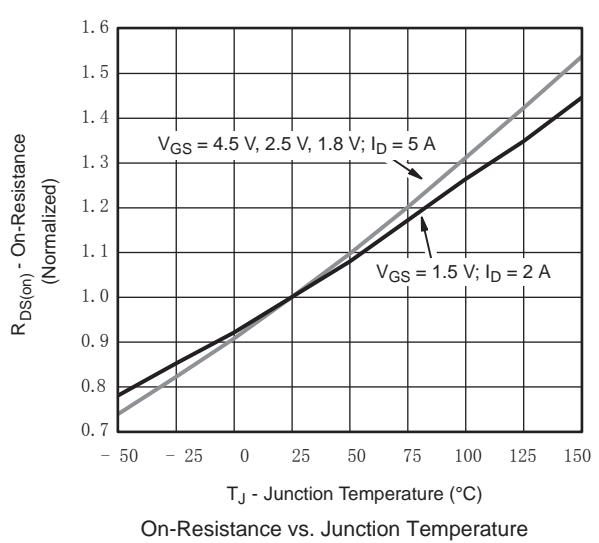
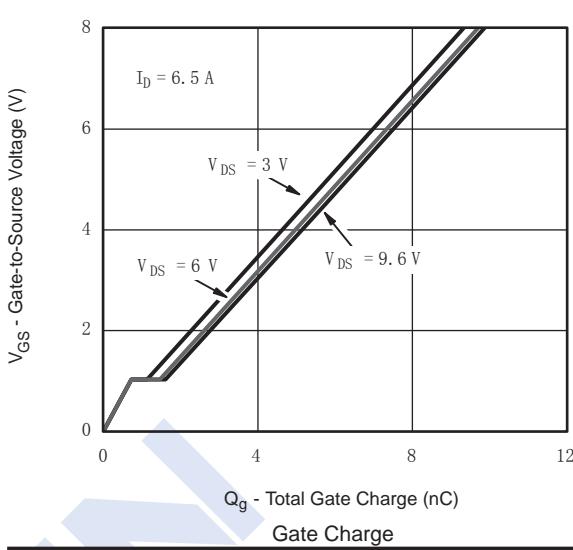
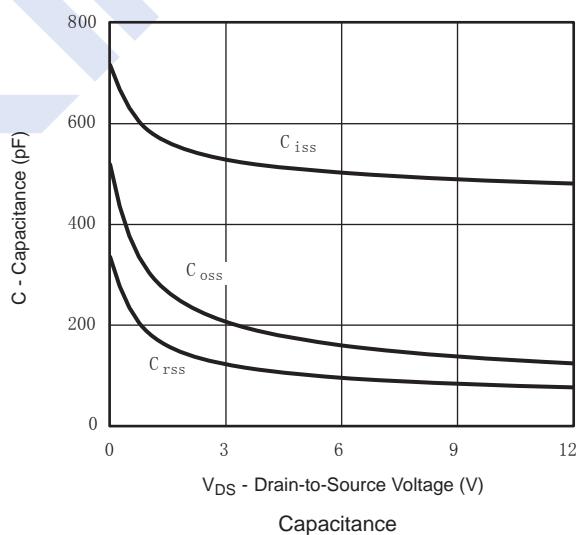
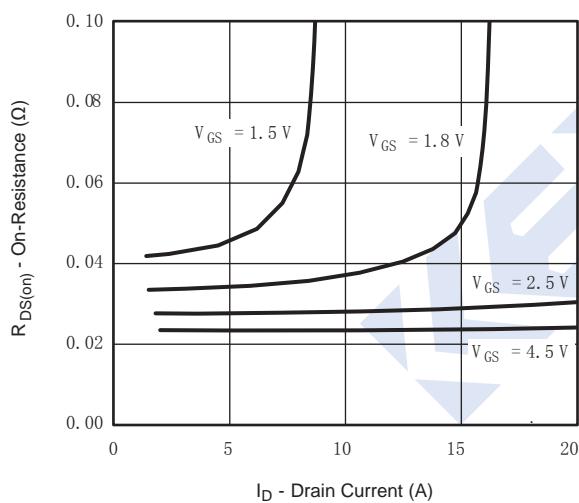
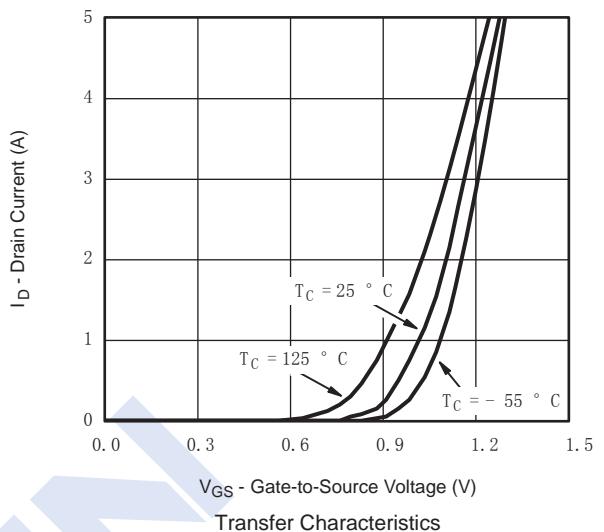
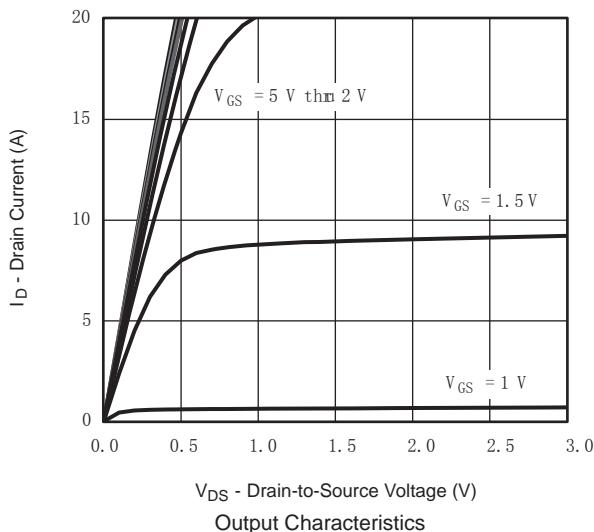
Turn-On DelayTime	$t_{d(on)}$	N-Channel: $V_{GS}=4.5V, V_{DS}=6V, I_D=5.2A,$ $R_L=1.2\Omega, R_{GEN}=1\Omega$ P-Channel: $V_{GS}=-4.5V, V_{DS}=-6V, I_D=-3.8A,$ $R_L=1.6\Omega, R_{GEN}=1\Omega$	N-CH	10	15	ns
Turn-On Rise Time	$t_r$		P-CH	30	40	
Turn-Off DelayTime	$t_{d(off)}$		N-CH	10	15	
Turn-Off Fall Time	$t_f$		P-CH	25	40	
Turn-On DelayTime	$t_{d(on)}$		N-CH	22	30	
Turn-On Rise Time	$t_r$		P-CH	30	45	
Turn-Off DelayTime	$t_{d(off)}$		N-CH	10	15	
Turn-Off Fall Time	$t_f$		P-CH	20	30	
Body Diode Reverse Recovery Time	$t_{rr}$	N-Channel $I_F = 5.2A, dI/dt = 100A/\mu s, T_J = 25^\circ C$ P-Channel $I_F = -3.8A, dI/dt = -100 A/\mu s, T_J = 25^\circ C$	N-CH	5	10	nC
Body Diode Reverse Recovery Charge	$Q_{rr}$		P-CH	8	15	
Reverse Recovery Fall Time	$t_a$		N-CH	10	15	
Reverse Recovery Rise Time	$t_b$		P-CH	12	20	
Maximum Body-Diode Continuous Current	$I_S$		N-CH	18	30	
Pulsed Body-Diode Current *	$I_{SM}$		P-CH	25	40	
Diode Forward Voltage	$V_{SD}$		N-CH	10	15	
			P-CH	18	30	
		$I_S=5.2A, V_{GS}=0V$	N-CH		4.5	A
		$I_S=-3.4A, V_{GS}=0V$	P-CH		-4.5	
			N-CH		20	V
			P-CH		-10	
			N-CH		1.2	V
			P-CH		-1.2	

Note. Pulse test; pulse width  $\leqslant 300 \mu s$ , duty cycle  $\leqslant 2\%$ .

## Complementary Trench MOSFET

2NP03

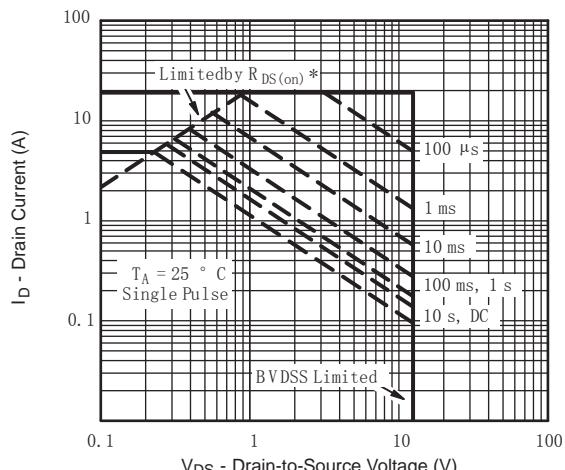
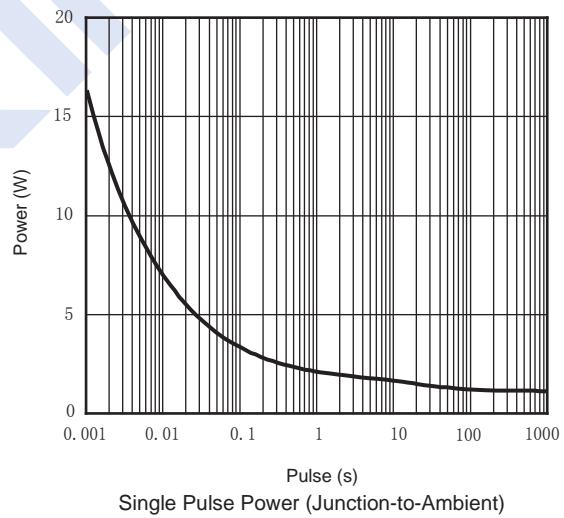
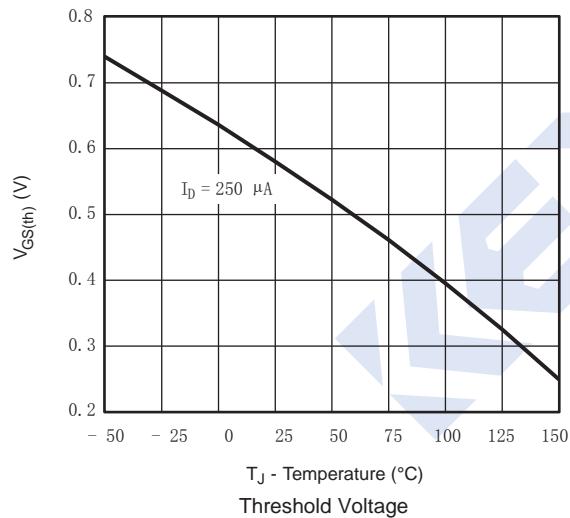
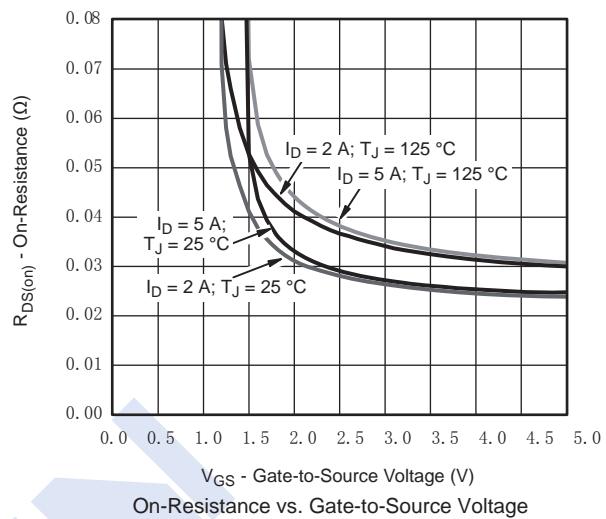
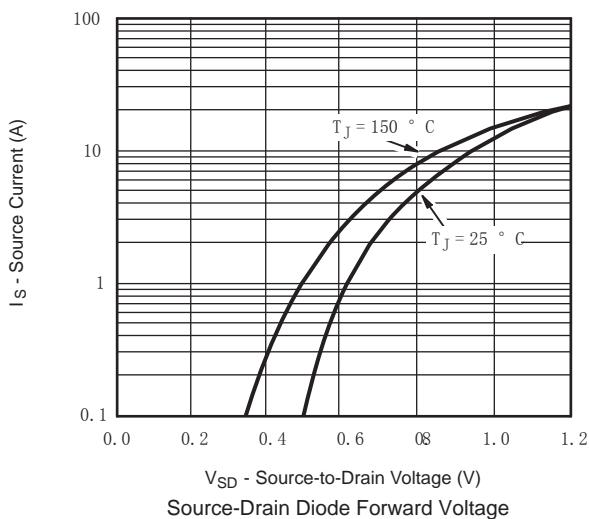
## ■ N-Channel Typical Characteristics



## Complementary Trench MOSFET

### 2NP03

■ N-Channel Typical Characteristics

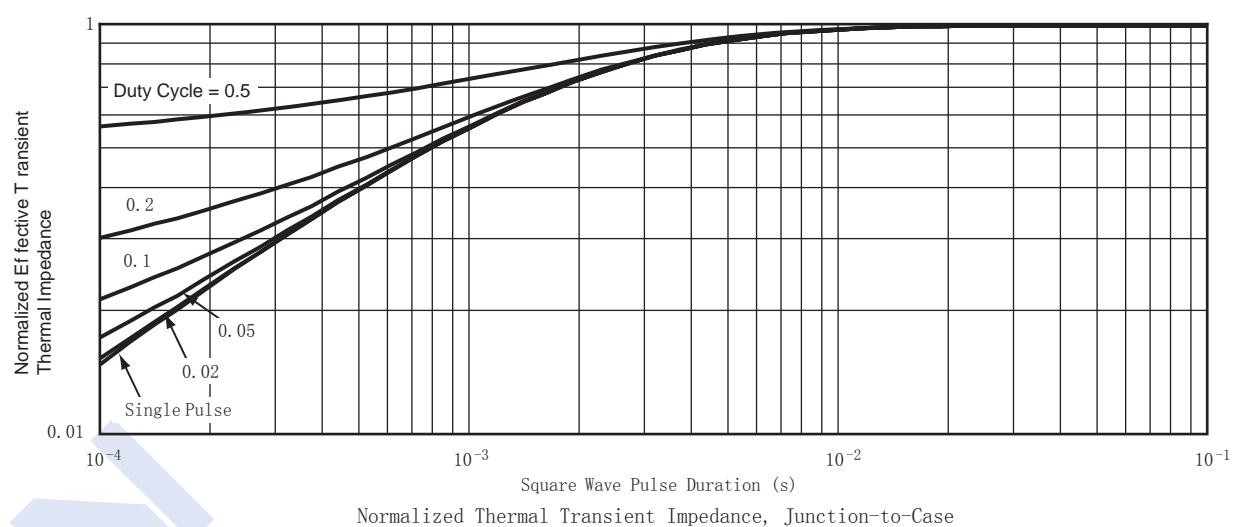
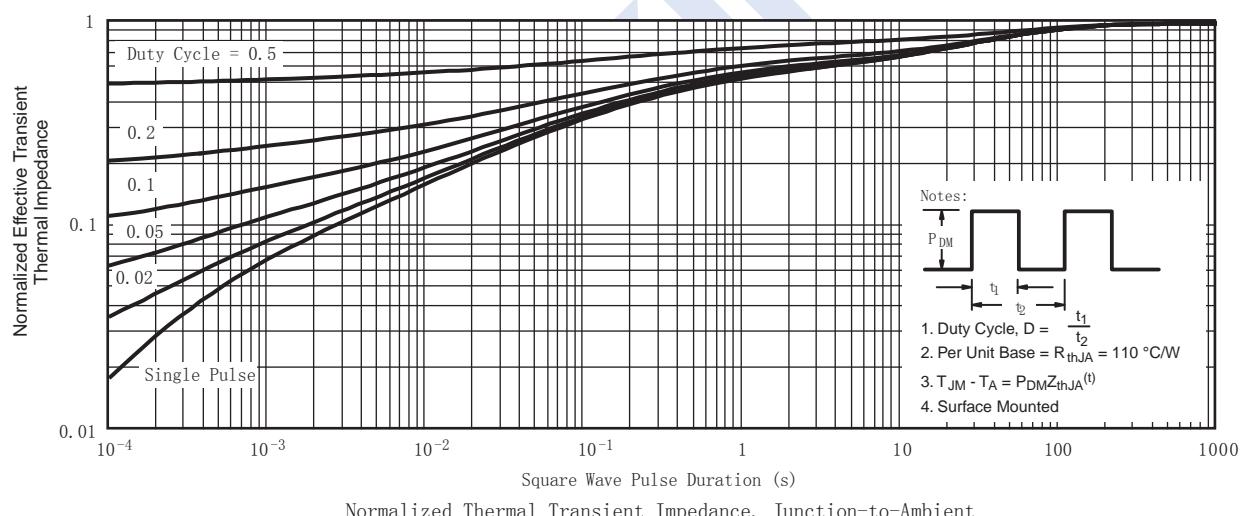
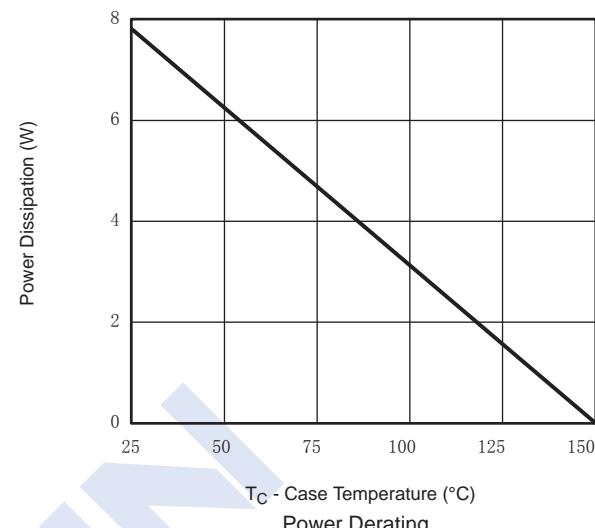
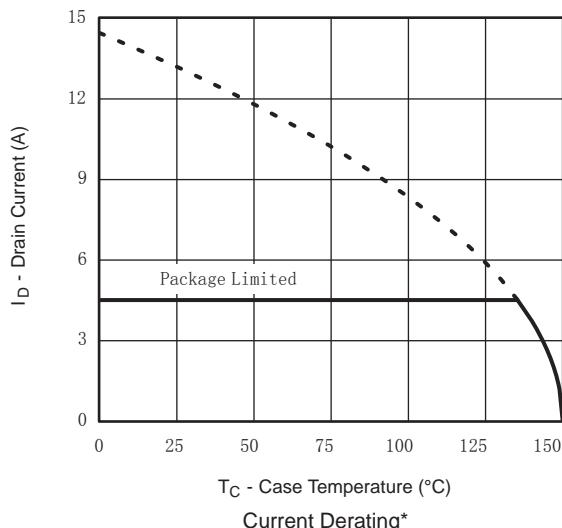


\*  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified  
Safe Operating Area, Junction-to-Ambient

## Complementary Trench MOSFET

### 2NP03

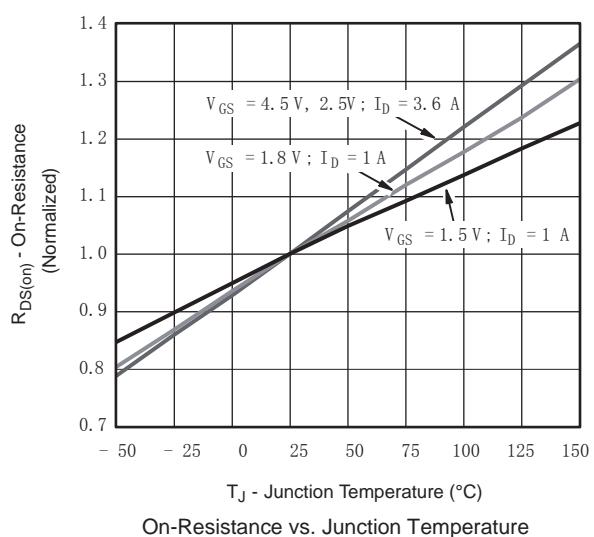
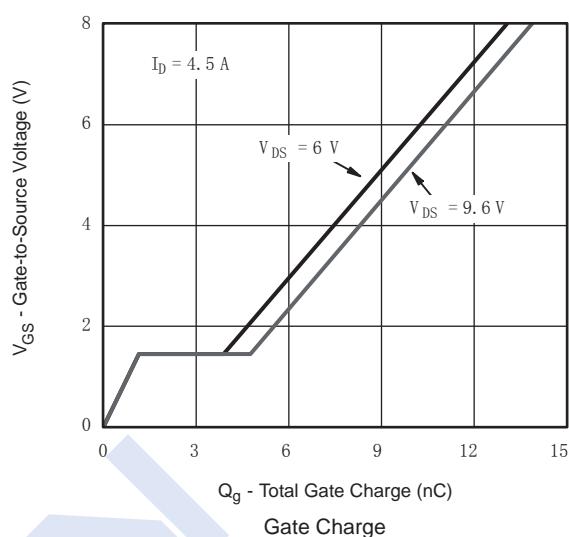
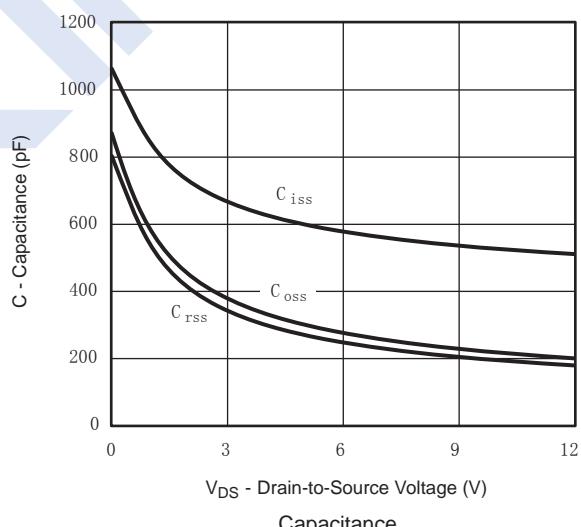
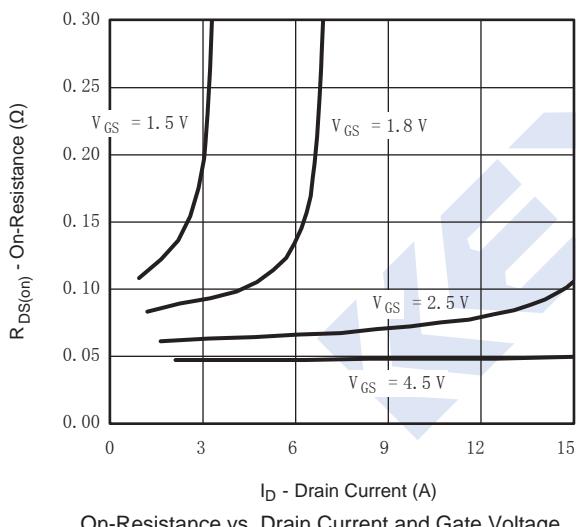
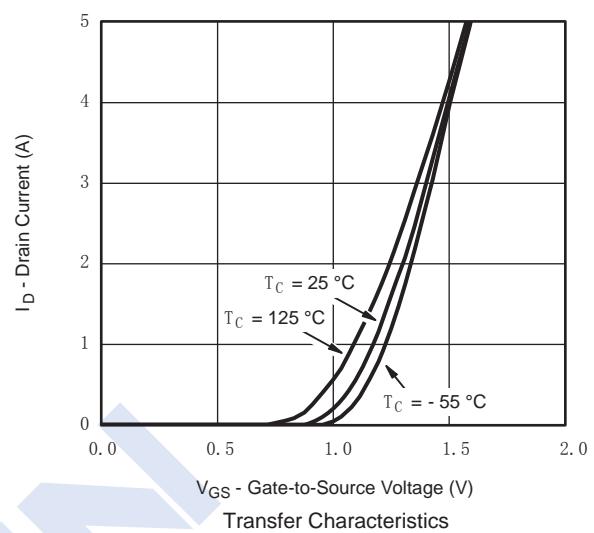
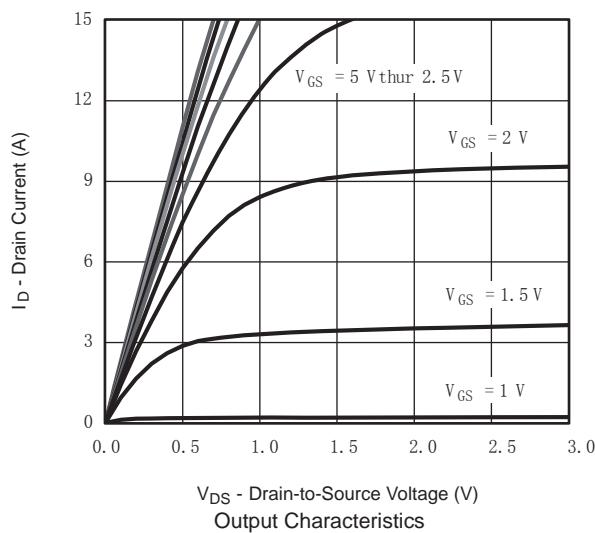
■ N-Channel Typical Characteristics



# Complementary Trench MOSFET

## 2NP03

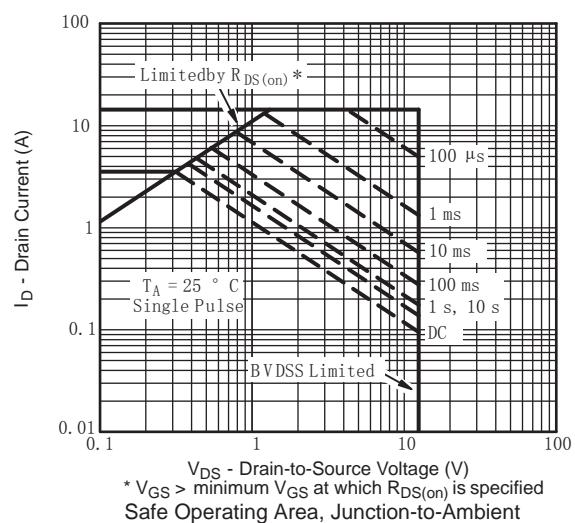
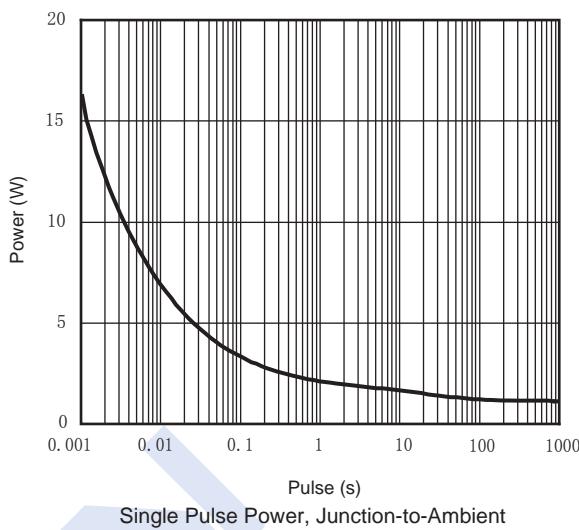
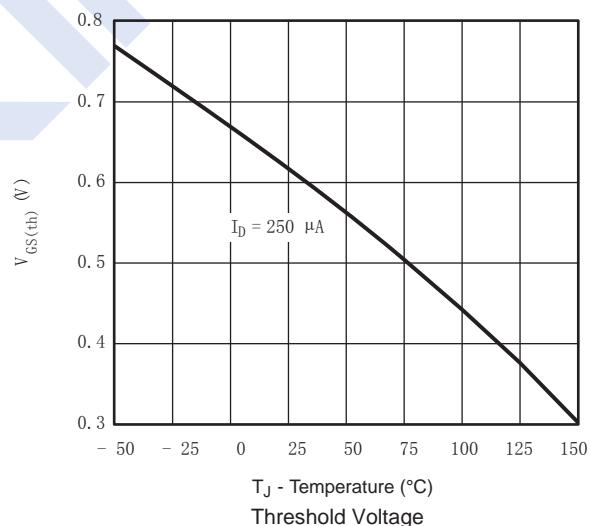
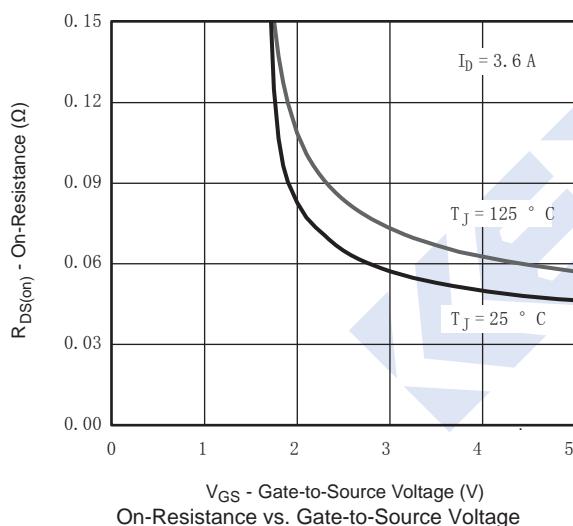
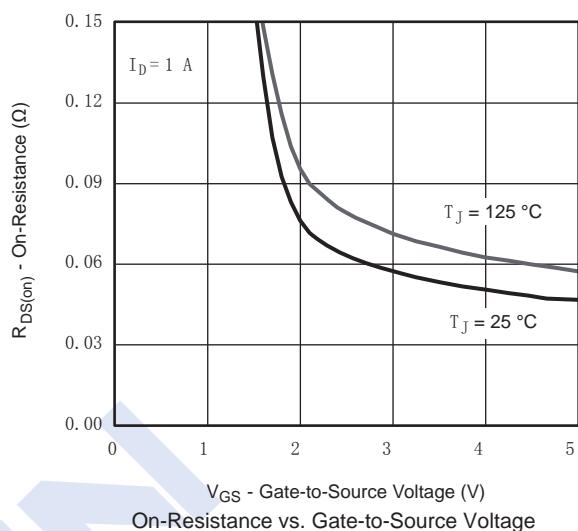
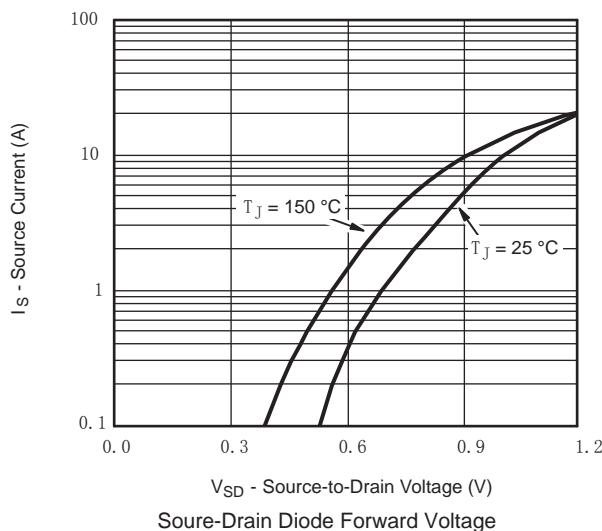
■ P-Channel Typical Characteristics



# Complementary Trench MOSFET

## 2NP03

■ P-Channel Typical Characteristics

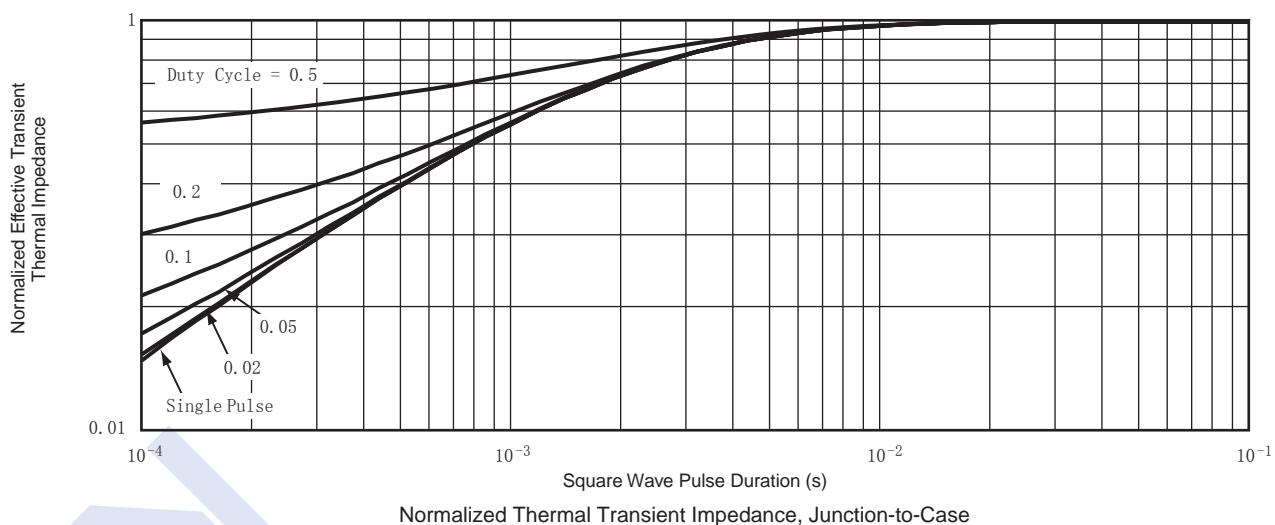
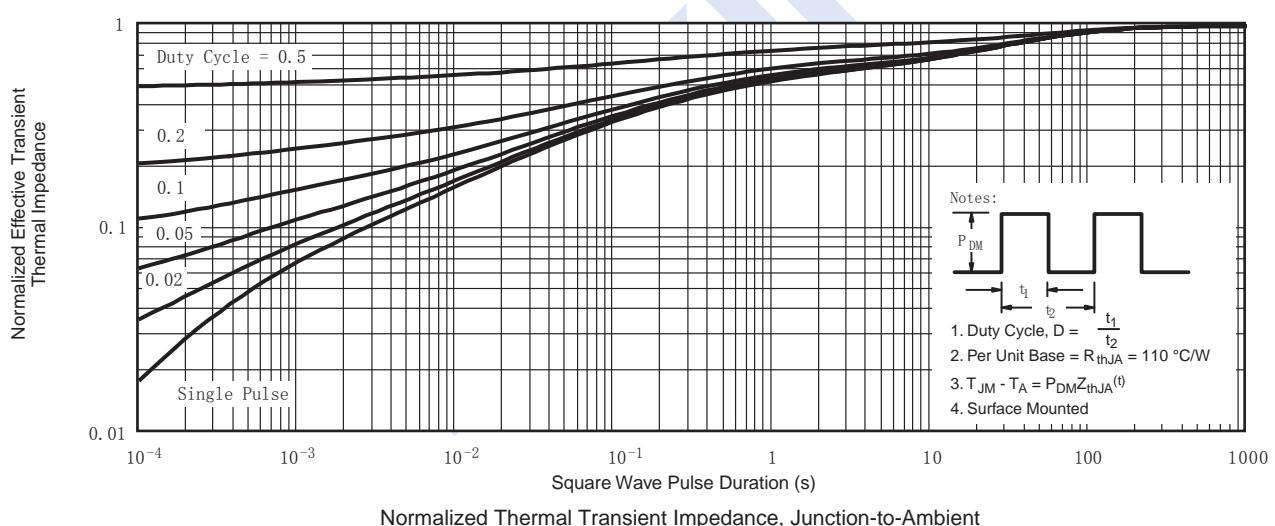
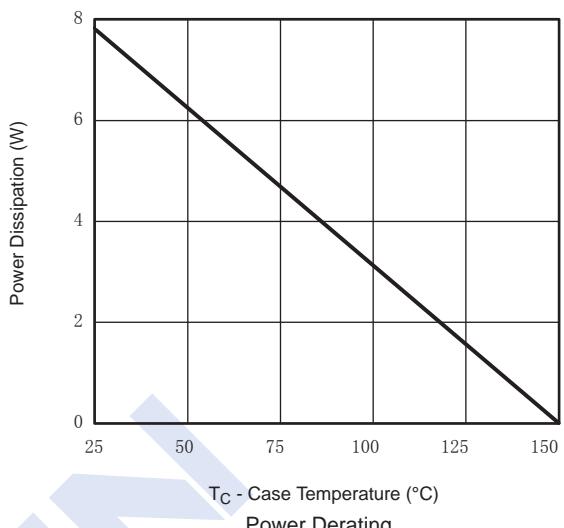
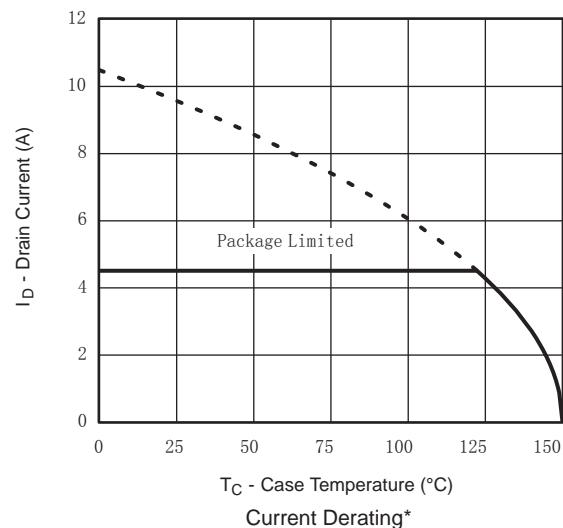


\*  $V_{GS} > \text{minimum } V_{GS}$  at which  $R_{DS(on)}$  is specified  
Safe Operating Area, Junction-to-Ambient

## Complementary Trench MOSFET

### 2NP03

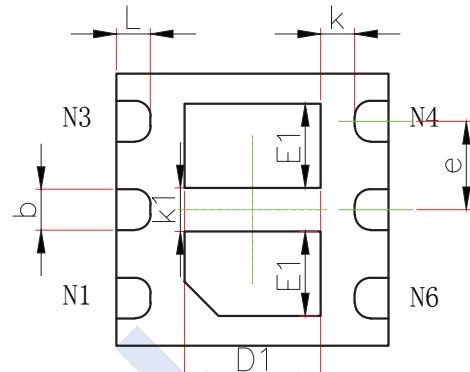
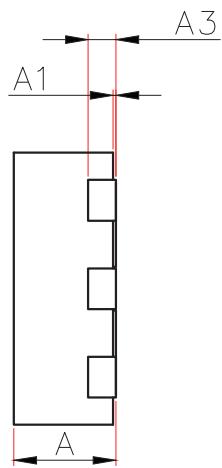
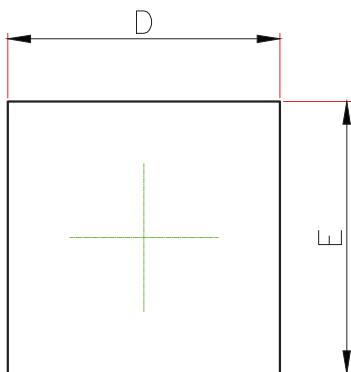
■ P-Channel Typical Characteristics



## Complementary Trench MOSFET

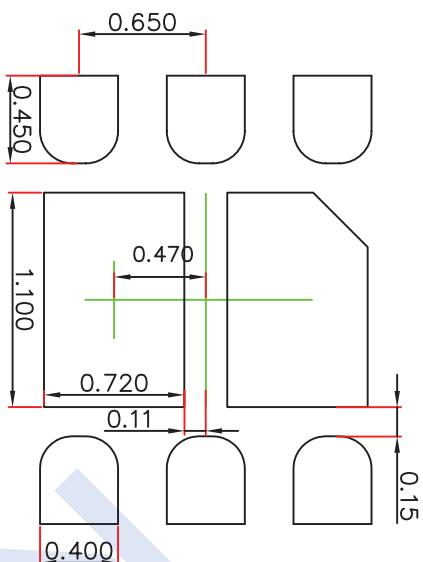
### 2NP03

#### ■ DFN2X2-6 Package Outline Dimensions



Symbol	Dimensions In Millimeter		Dimensions In Inches	
	MIN.	MAX.	MIN.	MAX.
A	0.450	0.650	0.019	0.026
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	1.900	2.100	0.075	0.083
E	1.900	2.100	0.075	0.083
D1	0.900	1.100	0.035	0.043
E1	0.520	0.720	0.020	0.028
b	0.250	0.350	0.010	0.014
e	0.625TYP.		0.025TYP.	
k	0.200MIN.		0.008MIN.	
k1	0.320REF.		0.013REF.	
L	0.200	0.300	0.008	0.012

#### ■ Suggested Pad Layout



#### Note:

1. Controlling dimension: in millimeters,
2. General tolerance:  $\pm 0.050\text{mm}$ ,
3. The pad layout is for reference purposes only.